

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
PETER HO	08/20/2010
PERQ-JON CHIA	09/27/2010
LAY-LAY CHUA	08/11/2010
RUI-QI PNG	08/20/2010
RICHARD HENRY FRIEND	08/22/2010
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<b>City:</b>	SINGAPORE
<b>State/Country:</b>	SINGAPORE
<b>Postal Code:</b>	119077
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14557493
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)816-4100
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<b>ATTORNEY DOCKET NUMBER:</b>	GPK-2490-63
<b>NAME OF SUBMITTER:</b>	GORDON P. KLANCNIK
<b>SIGNATURE:</b>	/Gordon P. Klancnik/
<b>DATE SIGNED:</b>	06/02/2017
<b>Total Attachments: 6</b>	

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source=2490-63\_Parent\_Assignment#page6.tif

# ASSIGNMENT OF PATENT APPLICATION

(Inventors) Peter HO  
 Perq-Jon CHIA  
 Lay-Lay CHUA  
 Rui-Qi PNG  
 Richard Henry FRIEND

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(Assignee) NATIONAL UNIVERSITY OF SINGAPORE

(Address) of 21 Lower Kent Ridge Road, Singapore 119077

(hereinafter designated as the Assignee) the undersigned's entire right, title and interest for the United States, its territories, dependencies and possessions, and for the country of

(Other

in the invention, and all application(s) for patent and any Letters Patent which may

Countries)

be granted therefor, known as

(Title)

MULTILAYER HETEROSTRUCTURES FOR APPLICATION IN OLEDs AND

PHOTOVOLTAIC DEVICES (Case No. 2490-46)

for which the undersigned has (have) executed on even date herewith an application for patent in the United States of America or, if not on even date, then has executed on or has already filed in

U.S. appln. Serial No. 12/744,800, filed on May 26, 2010.

The undersigned acknowledges an obligation of assignment of this invention to said assignee at the time the invention was made.

The undersigned agree(s) to execute all papers and documents necessary in connection with the application or any interference which may be declared and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient and further to perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patent of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of NIXON & VANDERHYE P.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document. It is understood and agreed that ASSIGNEE'S attorneys Nixon & Vanderhye P.C. have represented only ASSIGNEE and will continue to represent only ASSIGNEE with respect to this invention.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned signature(s).

Date _____	Signature of inventor _____	Peter HO
Date <u>27/9/10</u>	Signature of inventor _____	<i>Perq Jon</i> Perq-Jon CHIA
Date _____	Signature of inventor _____	Lay-Lay CHUA
Date _____	Signature of inventor _____	Rui-Qi PNG
Date _____	Signature of Inventor _____	Richard Henry FRIEND

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 (Title) **MULTILAYER HETEROSTRUCTURES FOR APPLICATION IN OLEDs AND PHOTOVOLTAIC DEVICES (Case No. 2490-46)**

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Date 20/8/2010 Signature of inventor

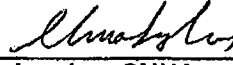


Peter HO

Date 2 Signature of inventor

Perq-Jon CHIA

Date 11/8/2010 Signature of inventor



Lay-Lay CHUA

Date 20/8/2010 Signature of inventor



Rui-Qi PNG

Date \_\_\_\_\_ Signature of inventor

Richard Henry FRIEND

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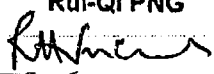
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		Peter HO
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		Perq-Jon CHIA
Date _____	Signature of inventor	_____
		Lay-Lay CHUA
Date _____	Signature of inventor	_____
		Rui-QI PNG
Date <u>22 Aug 2010</u>	Signature of inventor	
		Richard Henry FRIEND